Product & Service Specifications

Flexible Circuitry:  Multilayer Rigid-flex, Single & Double-Sided

Rigid Printed Wiring Boards:  Multilayer, Single & Double-Sided

Materials:  (RoHs Compliant)
- High Performance Flexible materials from DuPont (AP, FR, and LF).
- High Performance Laminates from Isola, Nelco, Arlon, Rogers, Gore, Taconic, and Ventec.
- Including Polyimide, FR4, Teflon, FR-27, FEP, and Ceramic filled composites.

Mechanical:
- Panel Size: 18” x 24” max; 12” x 18” min
- Layer Count: 24 max
- Hole Diameter: .004 drilled
- Line Width & Spacing: .003 min
- Dielectric Thickness Minimums: .001 Kapton, .002 (FR-4)
- Board Thickness: .125 max
- Aspect Ratio: 10:1
- Soldermask Clearance: .003 min, (1:1 With LDI Mask for Mask Defined BGA’s)
- UL approved unpierced Area: 4”

Finishes:
- Electroless Nickel Immersion Gold (ENIG)
- Electroless Nickel Electroless Palladium Immersion Gold (ENEPIG)
- Hot-Air Solder Leveled
- Immersion Silver
- Electrolytic Wire Bondable Gold
- Electrolytic Hard Gold

Coatings:
- LPI Soldermask, Green, Blue, Red, Black, White
- LDI Soldermask, Green Satin, Red Satin, Blue Satin
- Flexible LDI Mask, Amber
- Silk screen: InkJet White, LPI Red, LPI Black, LPI Yellow

Special Processes:
- Controlled Impedance
- Bare Back Flex (Dual Access)
- Blind & Buried Via’s
- Stacked Via’s
- Back Drilling
- Via Plugging: Conductive & Non-Conductive
- Controlled Depth Milling
- Edge Plating & Exposed Edge Plated Holes
- Discreet Gold Plating